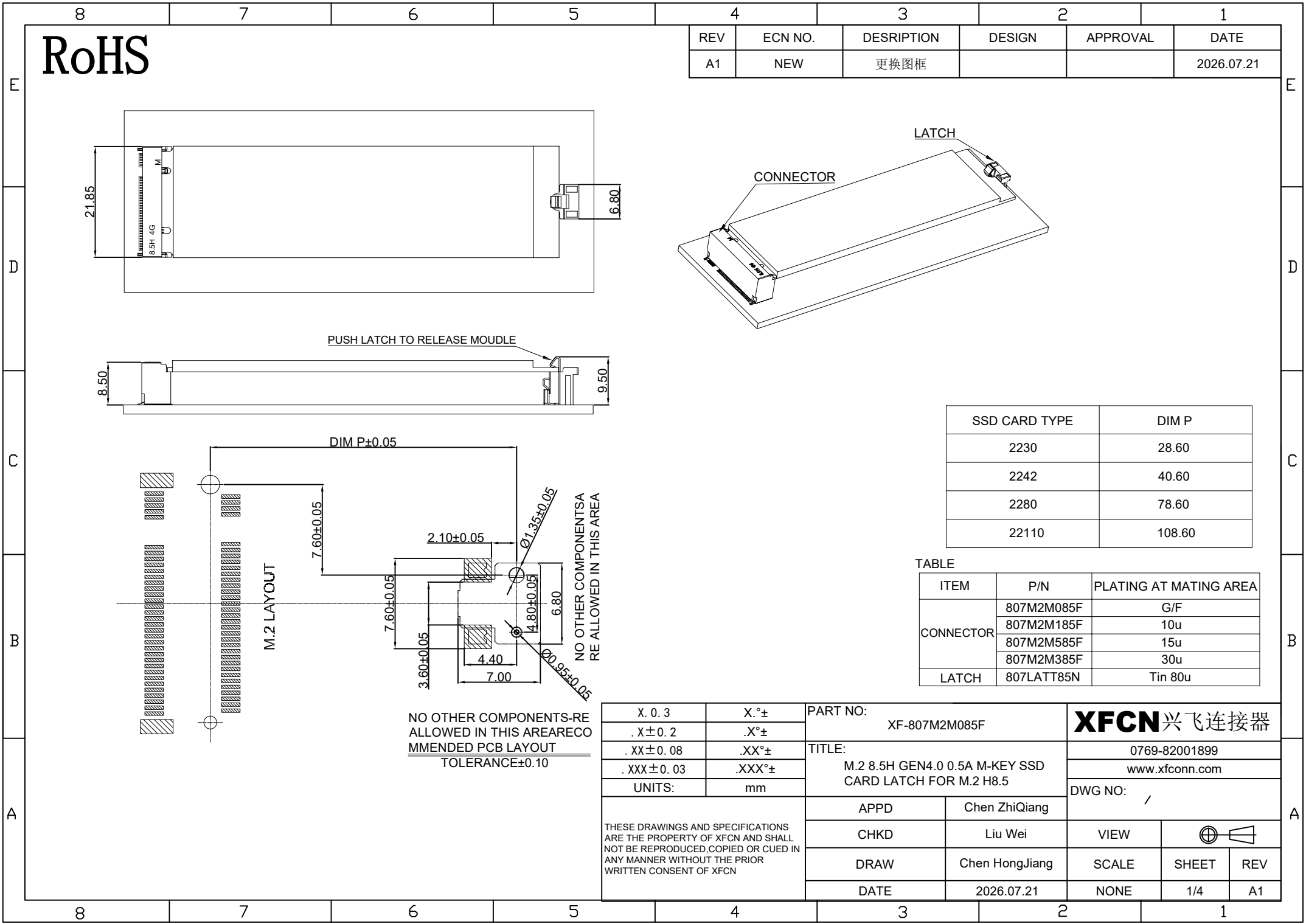
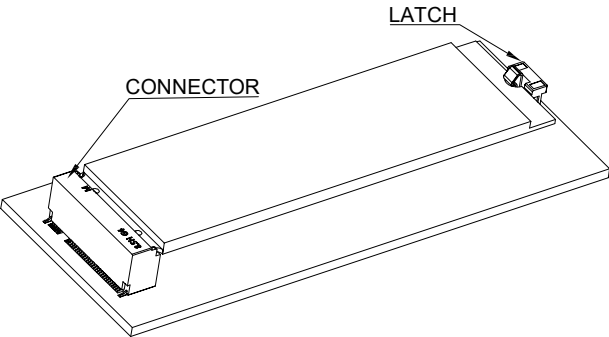




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SSD CARD TYPE	DIM P
2230	28.60
2242	40.60
2280	78.60
22110	108.60

TABLE		
ITEM	P/N	PLATING AT MATING AREA
CONNECTOR	807M2M085F	G/F
	807M2M185F	10u
	807M2M585F	15u
	807M2M385F	30u
LATCH	807LATT85N	Tin 80u

X. 0. 3	X. °±	PART NO: XF-807M2M085F		XFCN 兴飞连接器		
. X±0. 2	.X°±					
. XX±0. 08	.XX°±	TITLE: M.2 8.5H GEN4.0 0.5A M-KEY SSD CARD LATCH FOR M.2 H8.5		0769-82001899		
. XXX±0. 03	.XXX°±			www.xfconn.com		
UNITS:	mm			DWG NO: /		
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		CHKD	Liu Wei	VIEW		
		DRAW	Chen HongJiang	SCALE	SHEET	REV
		DATE	2026.07.21	NONE	1/4	A1

F



1.MATERIALS:

1.1 HOUSING:

1.2 CONTACT: GOLD PLATING AT MATING AREA (SEE P/N) G/F (1U" MIN.) AT SOLDER TAIL, ALL OVER NICKEL (50U" MIN.)

1.3PEG:50U"MIN.MATTE TIN PLATING OVER ALL,ALL OVER NICKEL(50U"MIN.)

2.FINISHED:ROSH2.0 AND HF COMPLIANT:

3. RATINGS

3.1VOLTAGE RATING:50V AC(PER PIN);

3.2CURRENT RATING:0.5A3.3OPERATING TEMPERATURE:-40 ~80 ;

4.ELECTRICAL REQUIREMENT:

4.1LLCR:55MΩ MAX,(INITIAL),20MΩ MAX.CHANGE ALLOWED(FINAL);

4.2DIELECTRIC WITHSTANDING VOLTAGE:300V AC(RMS)FOR 1 MINUTE:

4.3 INSULATION RESISTANCE: 500MΩ MIN. ⑨ 500V DC:

5.MECHANICAL REQUIREMENT

5.1MATING FORCE:25N MAX.

5.2 UNMATING FORCE: 25N MAX.

5.3DURABILITY:60 CYCLES:

5.4VBRATION:NO ELECTRICAL DISCONTINUITY GREATER THAN 1U
SEC SHALL OCCUR

6.RESISTANCE TO HEAT:THE TEMPERATURE SHALL BE $260\pm 5^{\circ}\text{C}$ 10 $\pm$ 1 SECONDS;

△

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RECOMMENDED PCB LAYOUT(TOP VIEW)
(DEFAULT TOLERANCE:±0.05mm)

TOP VIEW

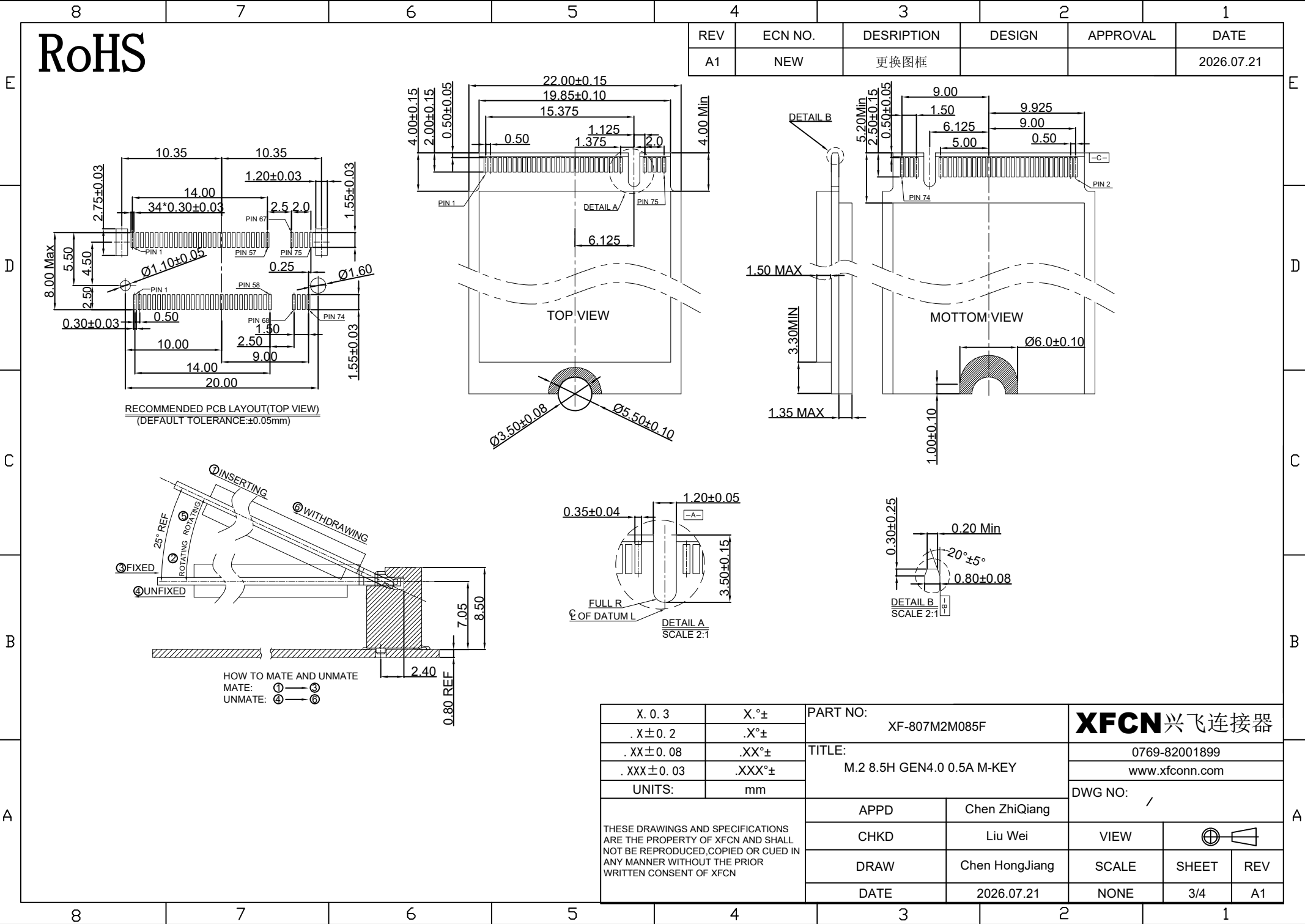
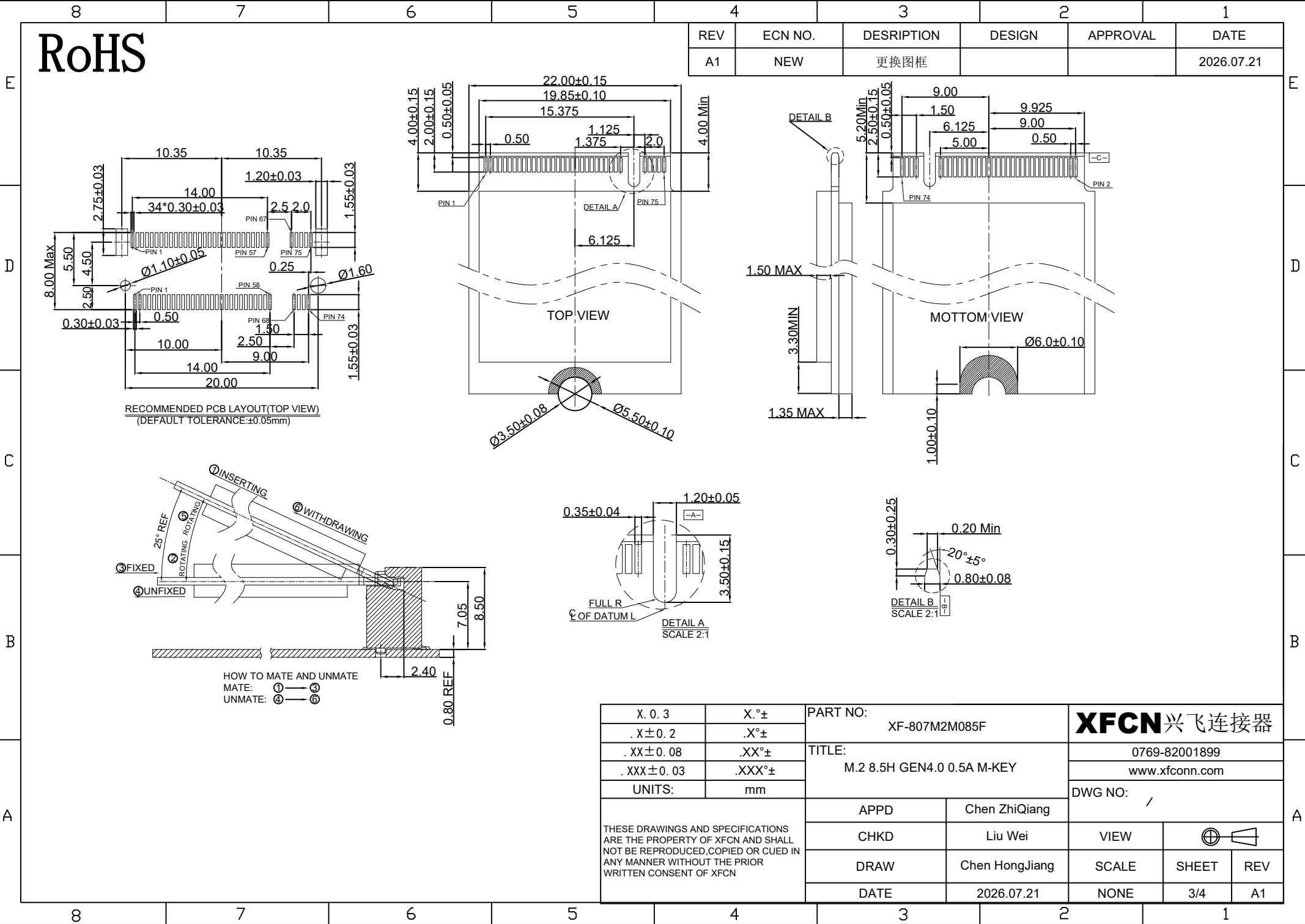
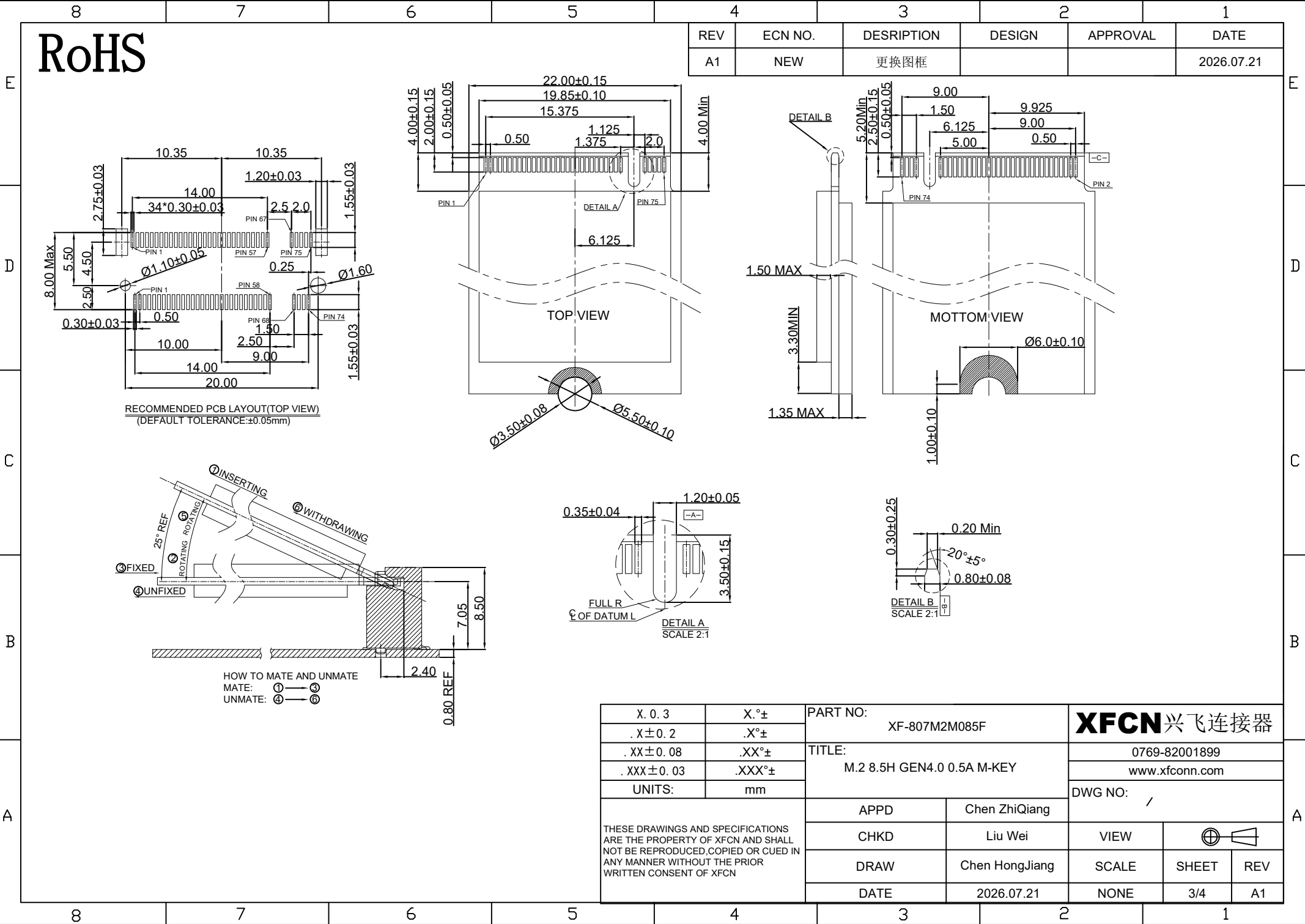
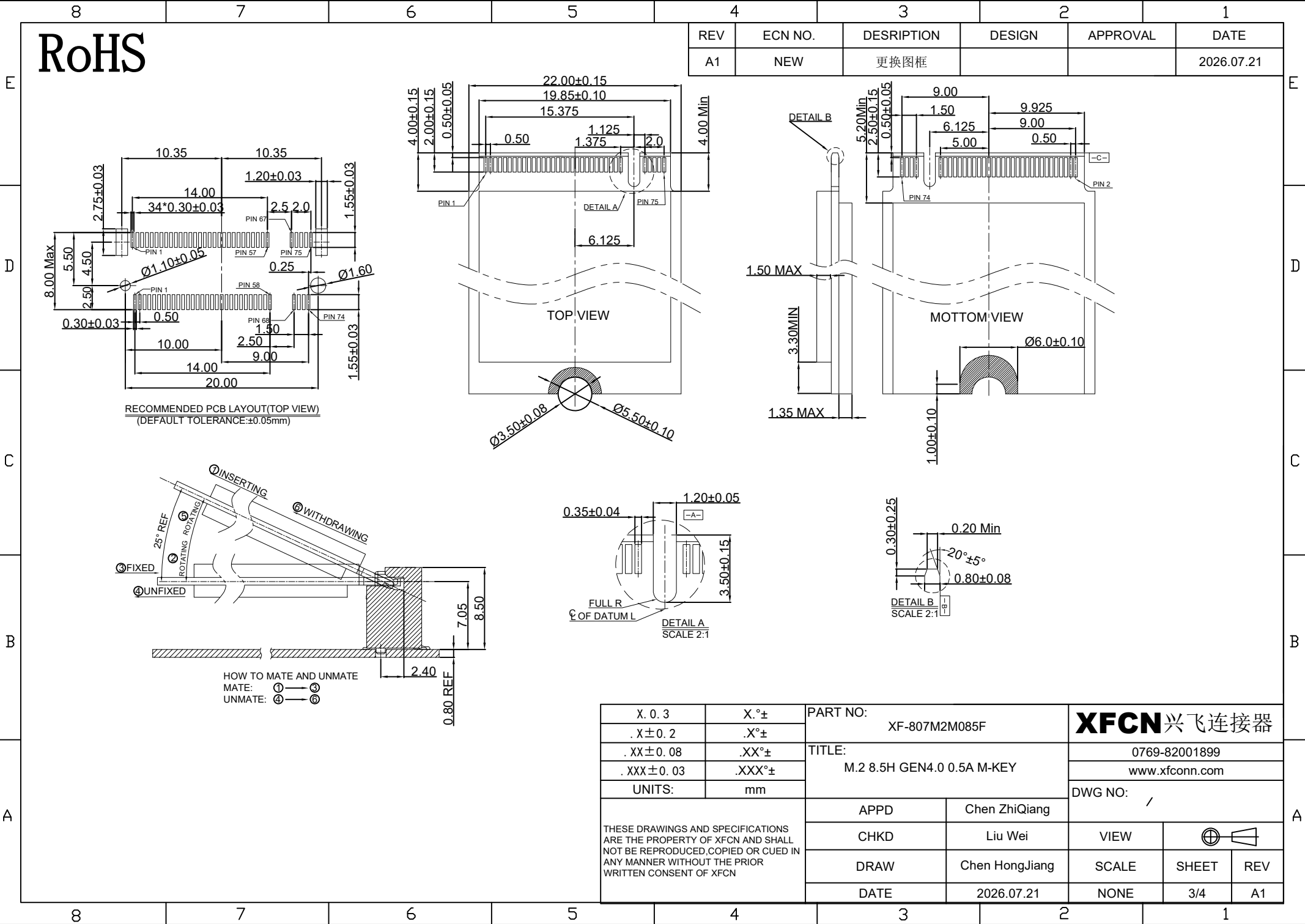
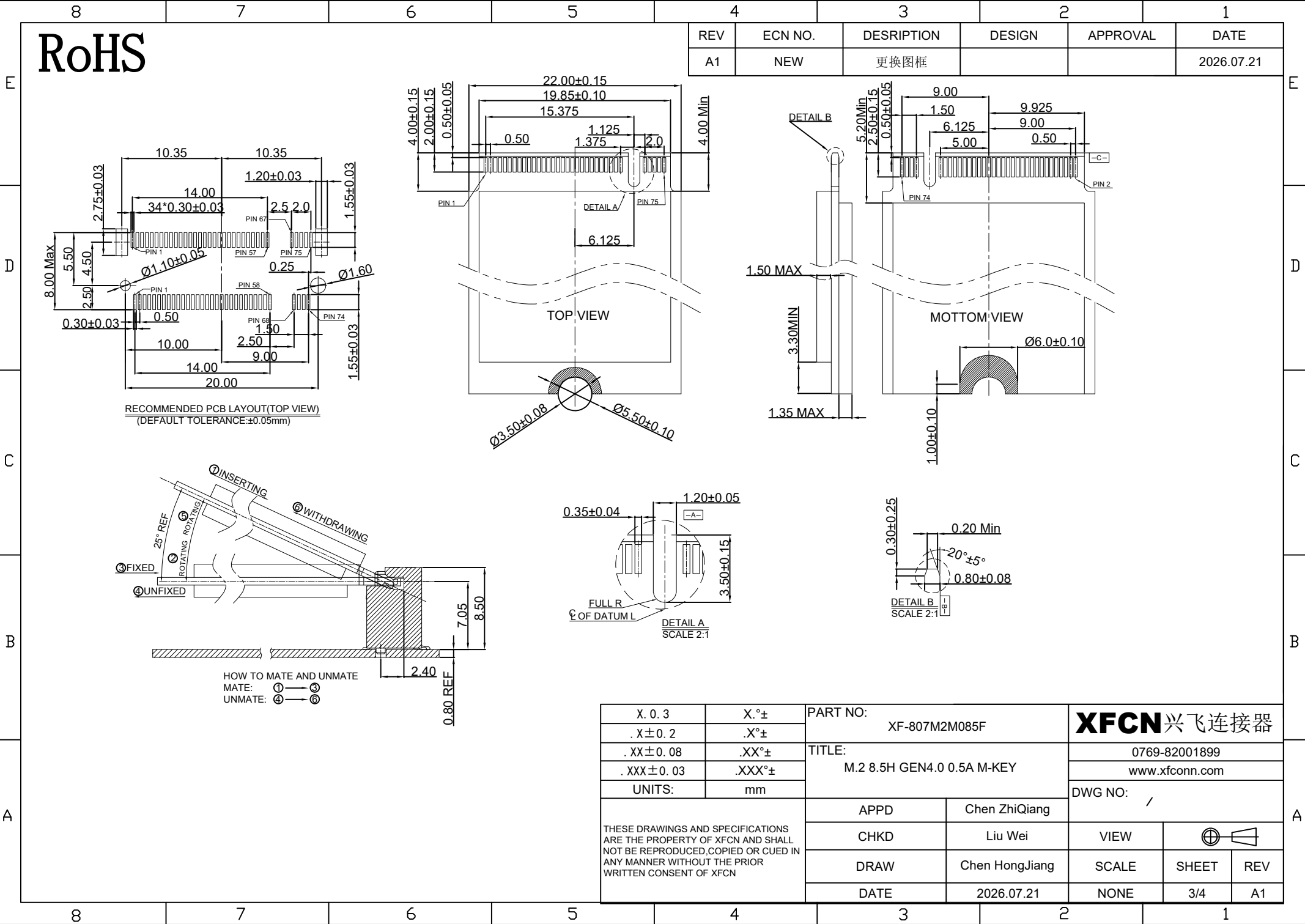
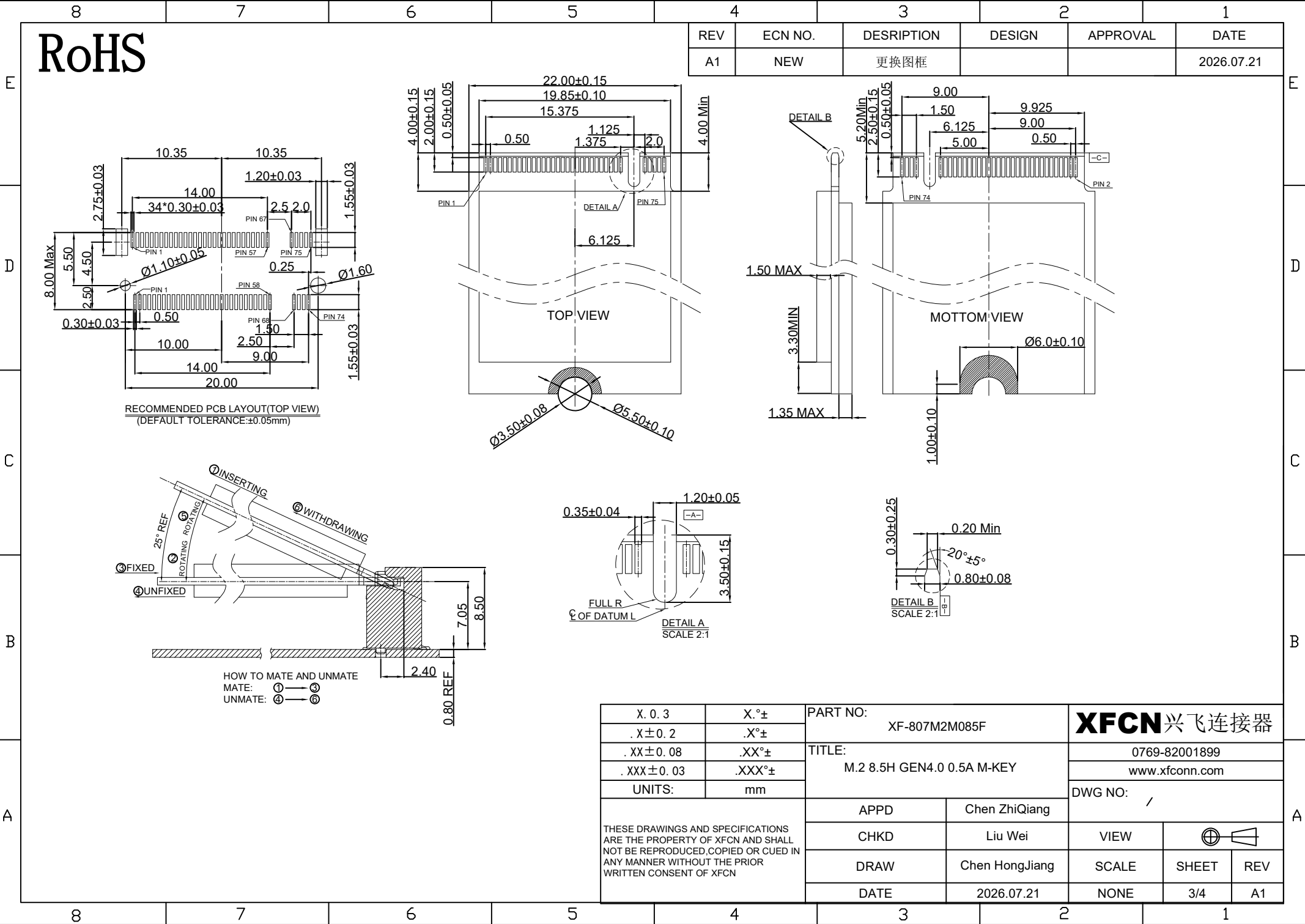
MOTTOM VIEW

DETAIL A
SCALE 2:1

DETAIL B
SCALE 2:1

HOW TO MATE AND UNMATE
MATE: ①→③
UNMATE: ④→⑥

X. 0. 3	X. ° ±	PART NO:	XFCN兴飞连接器				
. X ± 0. 2	. X° ±	XF-807M2M085F	0769-82001899				
. XX ± 0. 08	. XX° ±	TITLE:	www.xfconn.com				
. XXX ± 0. 03	. XXX° ±	M.2 85H GEN4.0 0.5A M-KEY					
UNITS:	mm	DWG NO:	/				
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		CHKD	Liu Wei	SCALE		SHEET	REV
		DRAW	Chen HongJiang	NONE		3/4	A1
		DATE	2026.07.21				

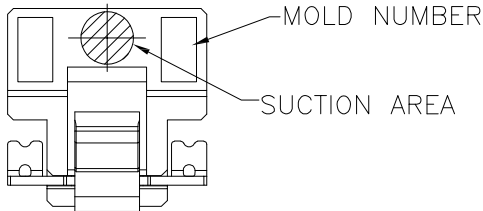
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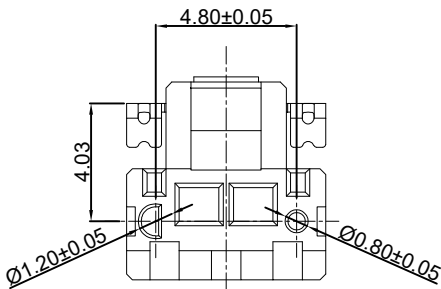
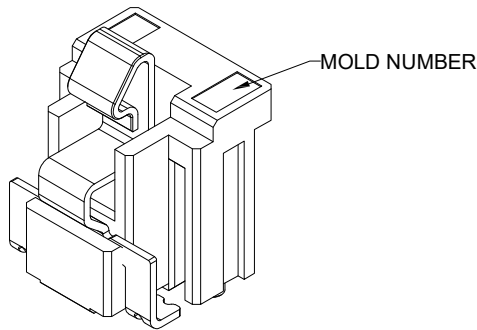
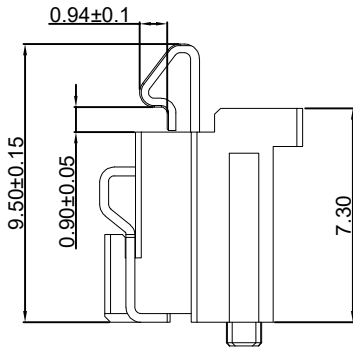
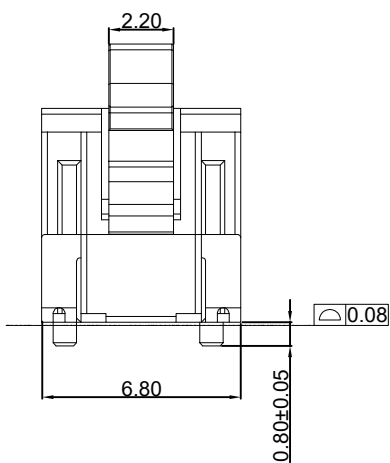
REV	ECN NO.	DESRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2026.07.21

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REV	ECN NO.	DESRPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2026.07.21



NOTES:
MATERIAL & FINISH
1.INSULATOR:LCP,UL94V-0 COLOR:BLACK
2.PEG:SUS304,T=0.30mm
3.PLATING:FITTING NAIL MATTE TIN 80u" TIN OVER NI 30u"MIN
4.OPERATING TEMPERATURE:-40~125°C



X. 0. 3	X. °±	PART NO: XF-807LATT85N		XFCN 兴飞连接器	
. X±0. 2	.X°±	TITLE: SSD CARD LATCH FOR M.2 H8.5		0769-82001899	
. XX±0. 08	.XX°±			www.xfconn.com	
. XXX±0. 03	.XXX°±			DWG NO: /	
UNITS:	mm	APPD	Chen ZhiQiang	VIEW	⊕
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		DRAW	Chen HongJiang		REV
		DATE	2026.07.21	NONE	4/4
					A1